

Specification for Approval

Date: 2021/10/05

Customer : _____

TAI-TECH P/N: ACM3225F2DV-102T08

CUSTOMER P/N: _____

DESCRIPTION: _____

QUANTITY: _____ pcs

REMARK:		
Customer Approval Feedback		

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APPROVED	CHECKED

R&D Center

APPROVED	CHECKED	DRAWN
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Wire Wound Type Common Mode Filter

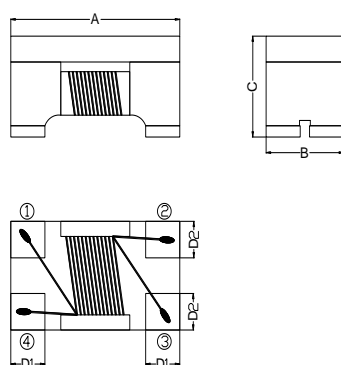
ACM3225F2DV-102T08

1. Features

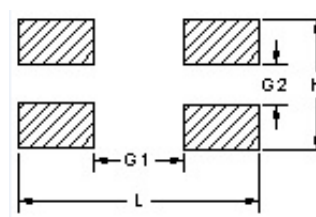
1. High common mode impedance at high frequency effects excellent noise suppression performance.
2. ACM3225F2DV series realizes small size and low profile 3.2x2.5x2.2 mm
3. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
4. High reliability -Reliability tests comply with AEC-Q200
5. Operating temperature -55~+150°C (Including self - temperature rise)



2. Dimension



Recommended PC Board Pattern



Series	A(mm)	B(mm)	C(mm)	D1(mm)	D2(mm)	L(mm)	H(mm)	G1(mm)	G2(mm)
3225F2DV	3.2±0.2	2.5±0.2	2.2±0.2	0.65±0.1	1.0±0.1	4.4	3.5	2.3	0.8

Units: mm

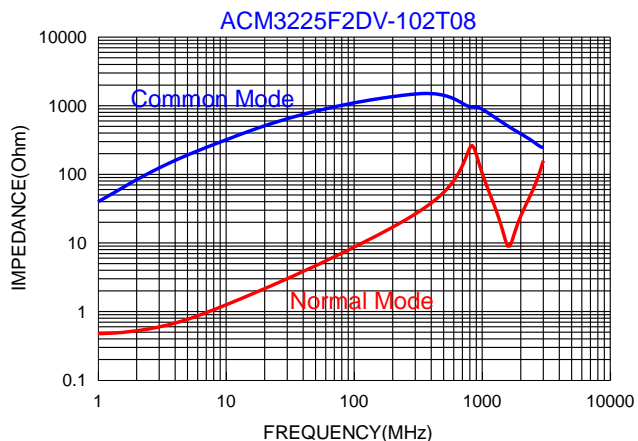
3. Part Numbering



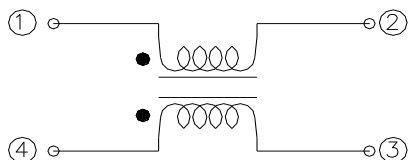
- A: Series
 B: Dimension
 C: Material Ferrite Core
 D: Number of Lines 2=2 lines
 E: Type W4D
 F: Category Code V=Vehicle
 G: Impedance 102=1000(Ω)
 H: Packaging T=Taping and Reel
 I: Rated Current 08=800mA

4. Specification

TAI-TECH Part Number	Common mode Impedance (Ω) [100MHz]	DC Resistance (Ω) max.	Rated Current (mA) max.	Rated voltage (Vdc) max.	IR (MΩ) min.
ACM3225F2DV-102T08	1000±25%	0.15	800	80	10

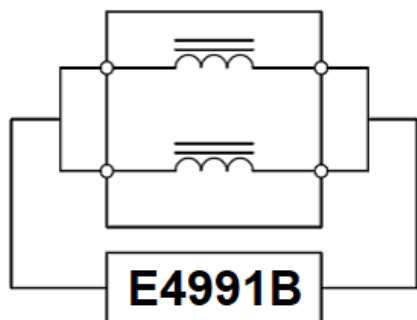


5. Schematic Diagram

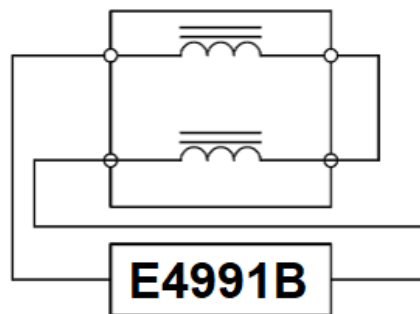


6. MEASURING CIRCUITS 2LINE

Common mode

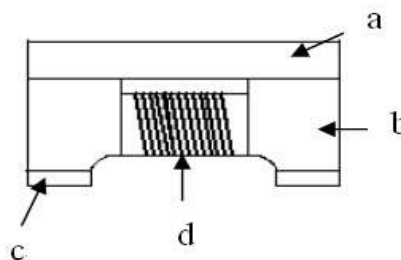


Differential mode



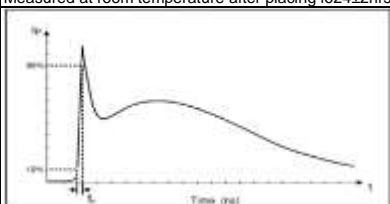
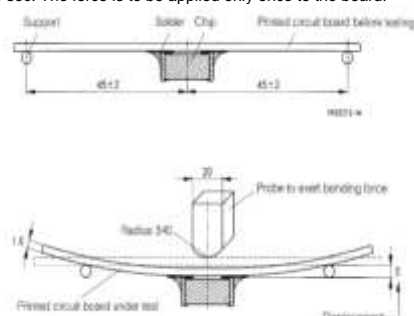
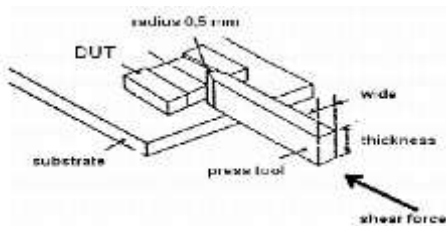
7. Materials

No.	Description	Specification
a.	Upper Plate	Ferrite
b.	Core	Ferrite Core
c.	Termination	Ag/Ni/Sn
d.	Wire	Enameled Copper Wire



8. Reliability and Test Condition

Item	Performance	Test Condition															
Operating temperature	-55~+150°C (Including self - temperature rise)																
Storage temperature	-55~+150°C (on board)																
Electrical Performance Test																	
Inductance	Refer to standard electrical characteristics list.	Keysight –E4980AL+ Keysight t -16334A															
DCR		Agilent-34420A Agilent-4338B															
I.R.		Chroma 19073															
Temperature Rise Test	Rated Current ΔT 40°C Max	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer															
Reliability Test																	
High Temperature Exposure(Storage) AEC-Q200	Appearance : No damage Impedance : within±15% of initial value Inductance : within±10% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Temperature : 150±2°C Duration : 1000hrs Min. Measured at room temperature after placing for 24±2 hrs															
Temperature Cycling AEC-Q200		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1 : -55±2°C 30min Min. Step2 : 150±2°C transition time 1min MAX. Step3 : 150±2°C 30min Min. Step4 : Low temp. Transition time 1min MAX. Number of cycles : 1000 Measured at room temperature after placing for 24±2 hrs															
Biased Humidity (AEC-Q200)		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Humidity : 85±3% R.H, Temperature : 85°C±2°C Duration: 1000hrs Min. Measured at room temperature after placing for 24±2hrs															
High Temperature Operational Life (AEC-Q200)		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Temperature : 150±2°C Duration : 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±2hrs															
External Visual	Appearance : No damage.	Inspect device construction, marking and workmanship. Electrical Test not required.															
Physical Dimension	According to the product specification size measurement	According to the product specification size measurement															
Resistance to Solvents	Appearance : No damage.	Add aqueous wash chemical - OKEM clean or equivalent.															
Mechanical Shock	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> <tr> <td>Lead</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> </tbody> </table> <p>Shocks in each direction along 3 perpendicular axes.</p>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	100	6	Half-sine	12.3	Lead	100	6	Half-sine	12.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec													
SMD	100	6	Half-sine	12.3													
Lead	100	6	Half-sine	12.3													

Item	Performance	Test Condition								
Vibration		IPC/JEDEC J-STD-020E Classification Reflow Profiles Oscillation Frequency:10Hz~2KHz~10Hz for 20 minute Equipment : Vibration checker Total Amplitude:5g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) ◦								
Resistance to Soldering Heat	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Test condition : <table border="1"> <thead> <tr> <th>Temperature(°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> <td>1</td> </tr> </tbody> </table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles							
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1							
Thermal shock (AEC-Q200)		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1 : -55±2°C 15±1min Step2 : 150±2°C within 20Sec. Step3 : 150±2°C 15±1min Number of cycles : 300 Measured at room temperature after placing fo24±2hrs								
ESD	Appearance : No damage.	 Direct Contact and Air Discharge PASSIVE COMPONENT HBM ESD Discharge Waveform to a Coaxial Target Test method: AEC-Q200-002 Test mode : Contact Discharge Discharge level : 4 KV (Level: 2)								
Solder ability	More than 95% of the terminal electrode should be covered with solder ◦	a. Method B, 4 hrs @155°C dry heat @235°C±5°C Testing Time :5 +0/-0.5 seconds b. Method D category 3. (8hours ± 15 min) @ 260°C±5°C Testing Time :30 +0/-0.5 seconds								
Electrical Characterization	Refer Specification for Approval	Summary to show Min, Max, Mean and Standard deviation .								
Flammability	Electrical Test not required.	V-0 or V-1 are acceptable.								
Board Flex	Appearance : No damage	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down. The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. The duration of the applied forces shall be 60 (+ 5) sec. The force is to be applied only once to the board. 								
Terminal Strength(SMD)	Appearance : No damage	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 								

9. Soldering and Mounting

9-1. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

9-1.1 IR Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

9-1.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 IR Soldering Reflow

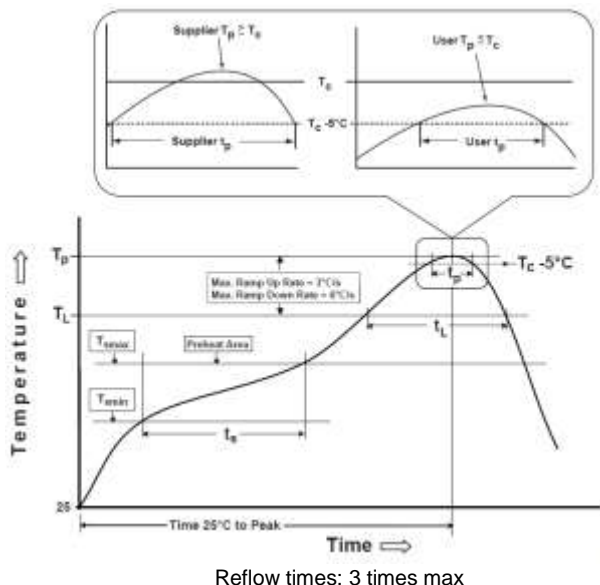


Fig.2 Iron soldering temperature profiles

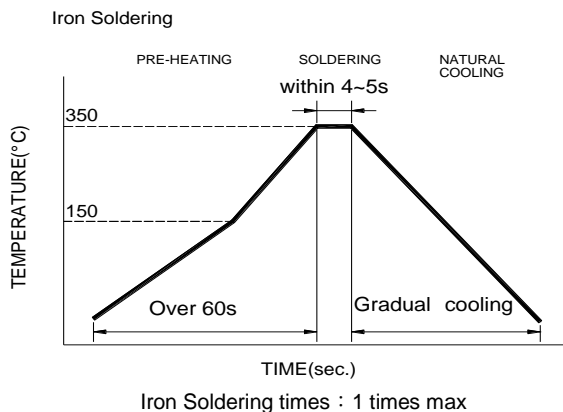


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	150°C 200°C 60-120seconds
Ramp-up rate(T_L to T_p)	3°C/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217°C 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	< 30 seconds
Ramp-down rate(T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p: maximum peak package body temperature, **T_c**: the classification temperature.

For user (customer) **T_p** should be equal to or less than **T_c**.

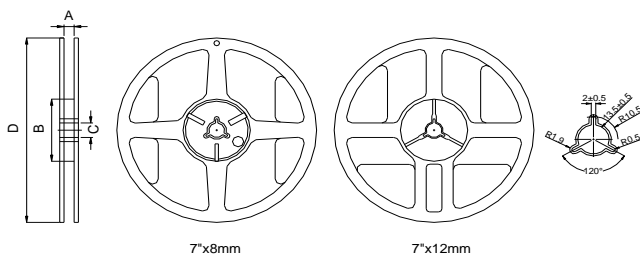
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E ◦

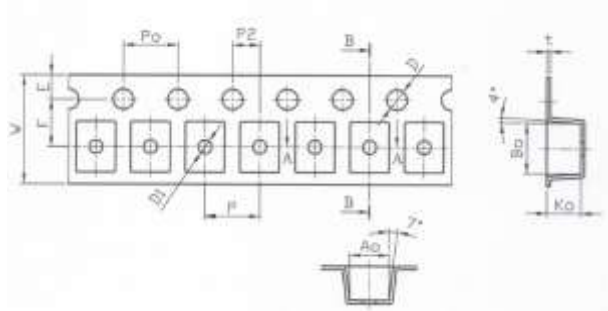
10. Packaging Information

10-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60.0±2.0	13.5±0.5	178.0±2.0

10-2. Tape Dimension / 8mm

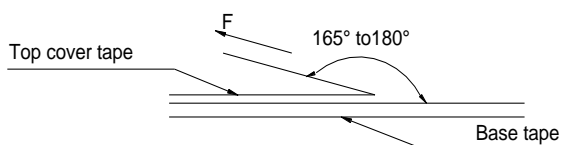


Series	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	D1(mm)	P0(mm)	A0(mm)	B0(mm)	K0(mm)	t(mm)
ACM3225F2D	8.00±0.10	4.00±0.10	1.75±0.10	3.50±0.05	2.00±0.05	1.50+0.10/-0.00	1.00±0.10	4.00±0.10	2.88±0.10	3.72±0.10	2.50±0.10	0.26±0.05

10-3. Packaging Quantity

Chip size	Chip/Reel	Inner Box	Middle Box	Carton
ACM3225F2D	2000	10000	50000	100000

10-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5-35	45-85	860-1060	300

Application Notice

- Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

- TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
- Temperature and humidity conditions: Less than 40°C and 60% RH.
- Recommended products should be used within 12 months form the time of delivery.
- The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation

- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- The use of tweezers or vacuum pick up is strongly recommended for individual components.
- Bulk handling should ensure that abrasion and mechanical shock are minimized.